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DOCKET NO.: MERCHANT 33-3-3

"Reply under 37 CFR 1.116  
--Expedited Procedure--  
Examining Group 2823

AT-12823

#18/ComdtB  
PATENT

CAEX  
April  
8/28/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Sailesh Merchant, *et. al.*

Serial No.: 09/092,158

Filed: June 5, 1998

For: METHOD FOR THE FABRICATION OF CONTACTS IN AN  
INTEGRATED CIRCUIT DEVICE

Grp./A.U.: 2823

Examiner: Eaton, K.

Honorable Commissioner of Patents  
Washington, D.C. 20231

Sir:

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on <u>8/17/2001</u> (Date)	
<u>Teague C. Eaton</u> (Printed or typed name of person signing the certificate)	
<u>Teague C. Eaton</u> (Signature of the person signing the certificate)	

**AMENDMENT UNDER 37 C.F.R. § 1.116**

In response to the Examiner's Action mailed June 20, 2001, please amend the above-identified application as follows:

**IN THE CLAIMS:**

(1) Kindly amend Claim 1 as follows:

1. (Twice Amended) A process for fabricating a contact in a semiconductor substrate having a contact opening formed therein, comprising: